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MOSFET - Power, Single N-Channel, PQFN8

100 V, 7.6 mΩ, 110 A

NTMFS7D8N10G

Features

- Wide SOA for Linear Mode Operation
- Low R_{DS(on)} to Minimize Conduction Loss
- High Peak UIS Current Capability for Ruggedness
- Small Footprint (5x6 mm) for Compact Design
- These Devices are Pb-Free, Halogen Free/BFR Free and are RoHS Compliant

Typical Applications

• 48 V Hot Swap System, Load Switch, Soft Start, E-Fuse

MAXIMUM RATINGS (T_J = 25°C, Unless otherwise specified)

Parameter			Symbol	Value	Unit
Drain-to-Source Voltage			V_{DSS}	100	V
Gate-to-Source Voltage			V_{GS}	±20	V
Continuous Drain Current R _{θJC} (Note 2)	Steady	T 05°C	I _D	110	Α
Power Dissipation R _{θJC} (Note 2)	State T _C = 25°C		P _D	187	W
Continuous Drain Current $R_{\theta JA}$ (Note 1, 2)	Steady State T _A = 25°C		I _D	14	Α
Power Dissipation R _{θJA} (Note 1, 2)	Otate		P _D	3	W
Pulsed Drain Current	T _A = 25°0	C, t _p = 10 μs	I _{DM}	1656	Α
Operating Junction and Storage Temperature Range			T _J , T _{stg}	–55 to +175	°C
Source Current (Body Diode)			I _S	155	Α
Single Pulse Drain-to-Source Avalanche Energy (I _{AV} = 70 A, L = 0.1 mH)			E _{AS}	245	mJ
Lead Temperature Soldering Reflow for Soldering Purposes (1/8" from case for 10 s)			T _L	260	°C

Stresses exceeding those listed in the Maximum Ratings table may damage the device. If any of these limits are exceeded, device functionality should not be assumed, damage may occur and reliability may be affected.

- 1. Surface-mounted on FR4 board using 1 in² pad size, 1 oz Cu pad.
- The entire application environment impacts the thermal resistance values shown, they are not constants and are only valid for the particular conditions noted.

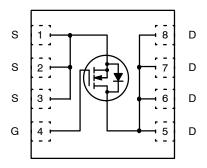


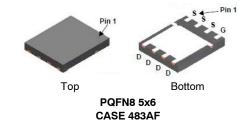
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V _{SSS}	R _{SS(ON)} MAX	I _D MAX
100 V	7.6 mΩ @ 10 V	110 A

N-Channel MOSFET





MARKING DIAGRAM



7D8N10 = Specific Device Code A = Assembly Location

Y = Year
W = Work Week
ZZ = Lot Traceability

ORDERING INFORMATION

See detailed ordering and shipping information on page 5 of this data sheet.

THERMAL CHARACTERISTICS

Symbol	Parameter	Max	Unit
$R_{ heta JC}$	Junction-to-Case - Steady State	0.8	°C/W
$R_{ hetaJA}$	Junction-to-Ambient - Steady State	50	

ELECTRICAL CHARACTERISTICS (T. 25°C unless athornies noted)

Parameter	Symbol	Test Conditions		Min	Тур	Max	Unit
OFF CHARACTERISTICS							
Drain – to – Source Breakdown Voltage	V _{(BR)DSS}	$V_{GS} = 0 \text{ V}, I_D = 250 \mu\text{A}$		100			V
Drain – to – Source Breakdown Voltage Temperature Coefficient	V _{(BR)DSS} / T _J	I _D = 250 μA, ref to 25°C			87.9		mV/°C
Zero Gate Voltage Drain Current	I _{DSS}	V _{GS} = 0 V, V _{DS} = 80 V	T _J = 25°C			1	μΑ
Gate – to – Source Leakage Current	1	$V_{DS} = 0 \text{ V}, V_{GS} = \pm 20 \text{ V}$				±100	nA
ON CHARACTERISTICS (Note 3)	I _{GSS}	v _{DS} = 0 v, v _{GS} =	120 V			±100	ПА
Gate Threshold Voltage	V-2	$V_{GS} = V_{DS}, I_D = 2$	054Λ	2.0	1	4.0	V
	V _{GS(TH)}	v _{GS} = v _{DS} , _{ID} = 2	254 μΑ	2.0	-9.4	4.0	mV/°C
Negative Threshold Temperature Coefficient	V _{GS(TH)} [/] T _J	I_D = 254 μ A, ref to 25°C			-9.4		IIIV/ C
Drain – to – Source On Resistance	R _{DS(on)}	V _{GS} = 10 V, I _D = 48 A			5.6	7.6	mΩ
Forward Transconductance	9FS	V _{DS} = 5 V, I _D = 48 A			37		S
Gate-Resistance	R _G	T _A = 25°C			0.33		Ω
CHARGES & CAPACITANCES							
Input Capacitance	C _{ISS}	V _{GS} = 0 V, f = 1 MHz, V _{DS} = 50 V			6180		pF
Output Capacitance	C _{OSS}				624.5		-
Reverse Transfer Capacitance	C _{RSS}				99		
Total Gate Charge	Q _{G(TOT)}	V _{GS} = 10 V, V _{DS} = 50 V, I _D = 48 A			92		nC
Gate-to-Source Charge	Q _{GS}				35		
Gate-to-Drain Charge	Q _{GD}				26		
Plateau Voltage	V _{GP}				6		V
SWITCHING CHARACTERISTICS (Note	3)						
Turn – On Delay Time	t _{d(ON)}	V_{GS} = 10 V, V_{DS} = 50 V, I_{D} = 48 A, R_{G} = 4.7 Ω			32		ns
Rise Time	t _r				24		
Turn – Off Delay Time	t _{d(OFF)}				51		
Fall Time	t _f				14		
DRAIN-SOURCE DIODE CHARACTER	STICS						
Forward Diode Voltage	V _{SD}	V _{GS} = 0 V, I _S = 48 A	T _J = 25°C		0.84		V
			T _J = 125°C		0.73		
Reverse Recovery Time	t _{RR}	V_{GS} = 0 V, dI_S/dt = 300 A/ μ s, I_S = 24 A			42		ns
Reverse Recovery Charge	Q _{RR}				177		nC
Reverse Recovery Time	t _{RR}	$V_{GS} = 0 \text{ V, dI}_S/\text{dt} = 1000 \text{ A/}\mu\text{s,}$ $I_S = 24 \text{ A}$			33		ns
Reverse Recovery Charge	Q _{RR}				411		nC

Product parametric performance is indicated in the Electrical Characteristics for the listed test conditions, unless otherwise noted. Product performance may not be indicated by the Electrical Characteristics if operated under different conditions.

3. Switching characteristics are independent of operating junction temperatures.

TYPICAL CHARACTERISTICS

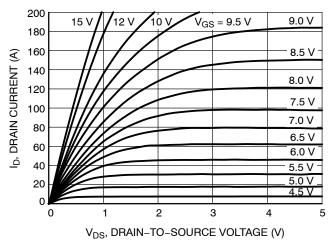


Figure 1. On-Region Characteristics

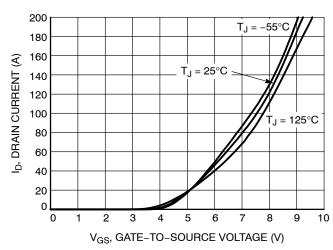


Figure 2. Transfer Characteristics

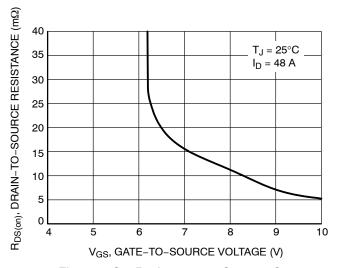


Figure 3. On-Resistance vs. Gate-to-Source Voltage

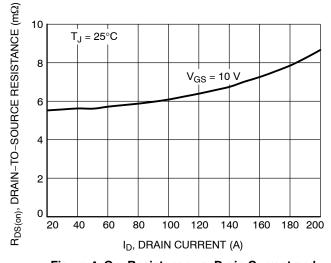


Figure 4. On-Resistance vs. Drain Current and Gate Voltage

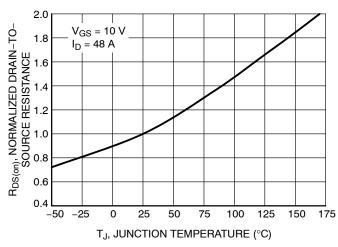


Figure 5. On–Resistance Variation with Temperature

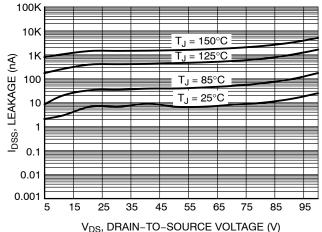


Figure 6. Drain-to-Source Leakage Current vs. Voltage

TYPICAL CHARACTERISTICS

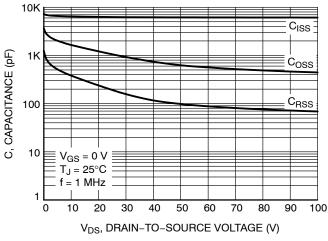


Figure 7. Capacitance Variation

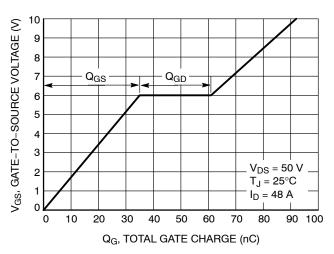


Figure 8. Gate-to-Source Voltage vs. Total Charge

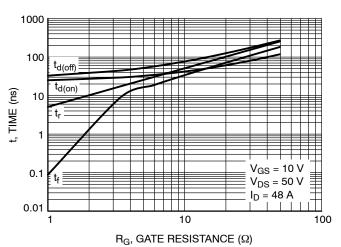


Figure 9. Resistive Switching Time Variation vs. Gate Resistance

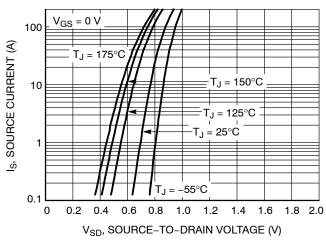


Figure 10. Diode Forward Voltage vs. Current

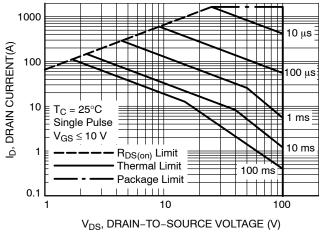


Figure 11. Maximum Rated Forward Biased Safe Operating Area

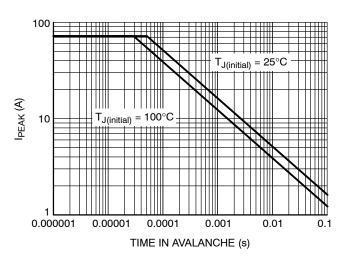


Figure 12. I_{PEAK} vs. Time in Avalanche

TYPICAL CHARACTERISTICS

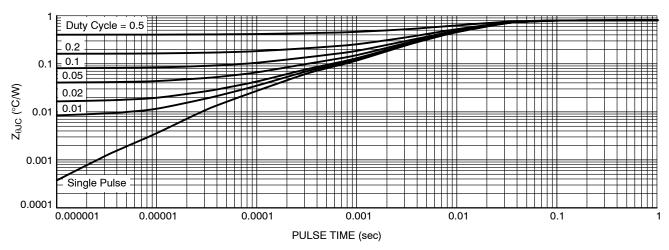


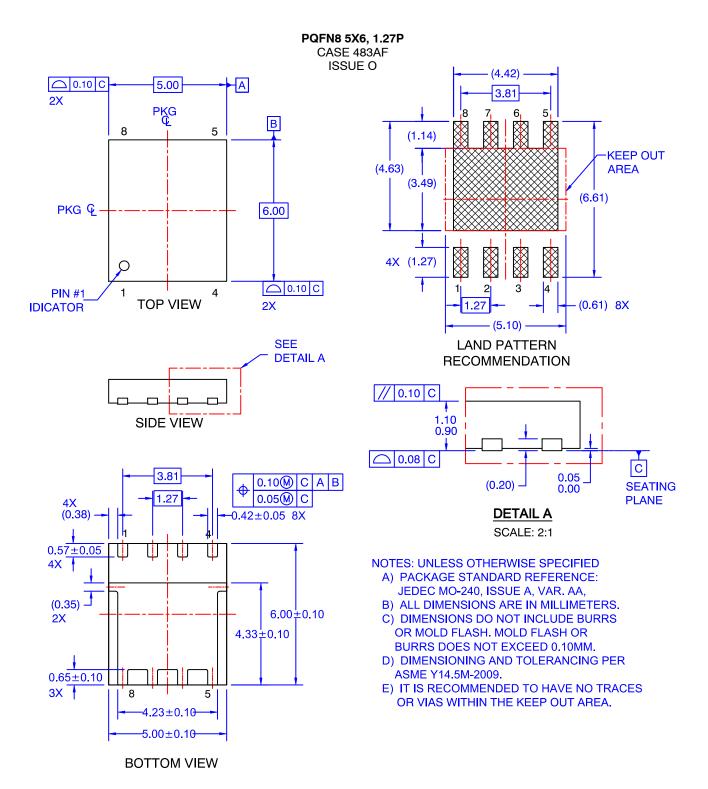
Figure 13. Thermal Characteristics

ORDERING INFORMATION

Device	Device Marking	Package	Shipping [†]
NTMFS7D8N10G	7D8N10	PQFN8 5x6 (Pb–Free/Halogen Free)	3000 / Tape & Reel

[†]For information on tape and reel specifications, including part orientation and tape sizes, please refer to our Tape and Reel Packaging Specifications Brochure, BRD8011/D.

PACKAGE DIMENSIONS



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